



KD3407SRG

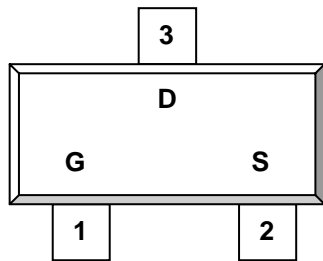
P Channel Enhancement Mode MOSFET

DESCRIPTION

-3.6A

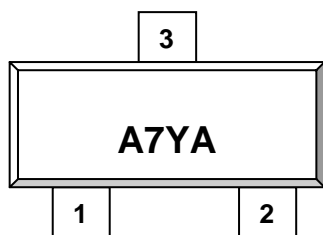
KD3407SRG is the P-Channel logic enhancement mode power field effect transistor which is produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application such as cellular phone and notebook computer power management, other battery powered circuits, and low in-line power loss are required. The product is in a very small outline surface mount package.

PIN CONFIGURATION SOT-23



1.Gate 2.Source 3.Drain

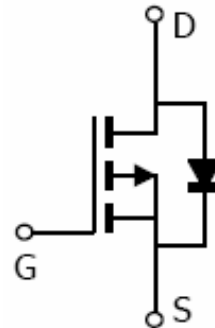
PART MARKING SOT-23



Y: Year Code A: Process Code

FEATURE

- -30V/-4.0A, $R_{DS(ON)} = 54m\Omega$ (Typ.) @ $V_{GS} = -10V$
- -30V/-3.2A, $R_{DS(ON)} = 80m\Omega$ @ $V_{GS} = -4.5V$
- Super high density cell design for extremely low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- SOT-23 package design



ORDERING INFORMATION

Part Number	Package	Part Marking
KD3407SRG	SOT-23	A7YA

※ Process Code : A ~ Z ; a ~ z

※ KD3407SRG S 23: SOT-23 ; R : Tape Reel ; G : Pb - Free

P Channel Enhancement Mode MOSFET

-3.6A

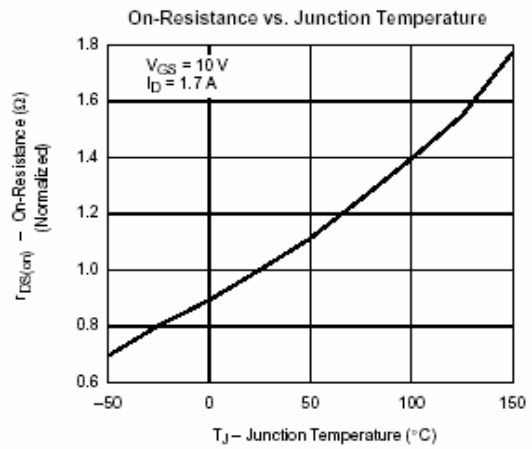
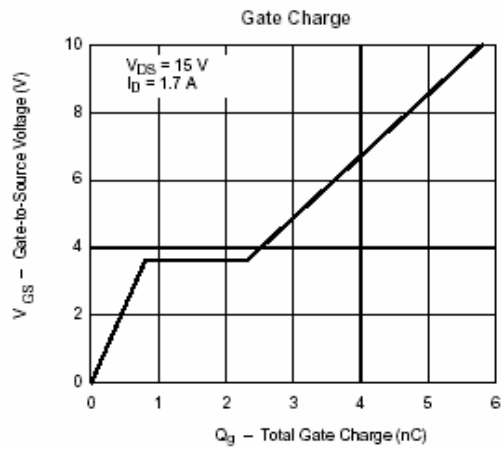
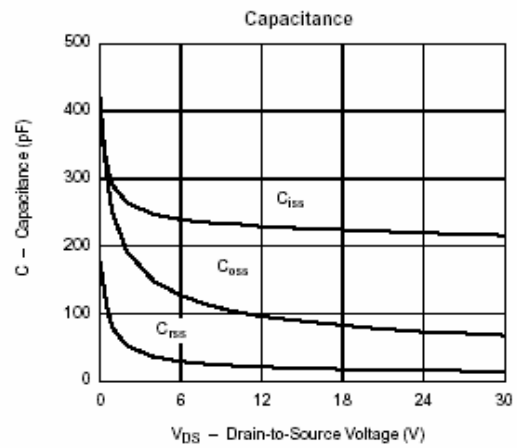
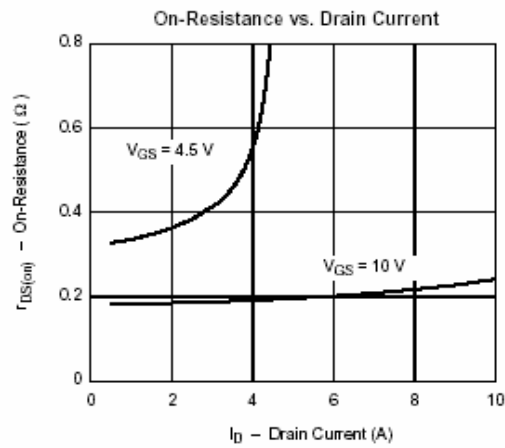
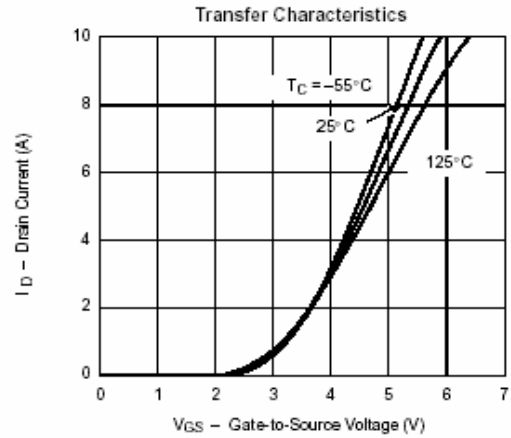
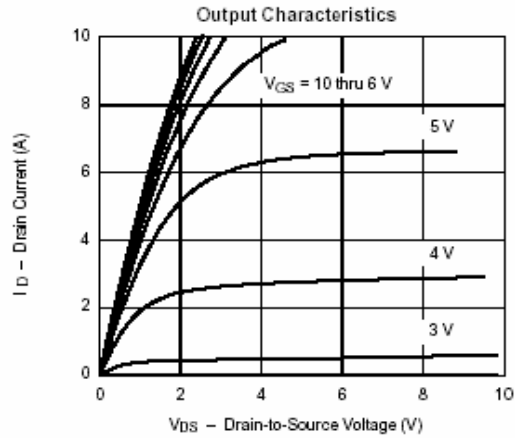
ABSOLUTE MAXIMUM RATINGS (Ta = 25°C Unless otherwise noted)

Parameter	Symbol	Typical	Unit
Drain-Source Voltage	V _{DSS}	-30	V
Gate-Source Voltage	V _{GSS}	±20	V
Continuous Drain Current (T _J =150°C)	I _D	T _A =25°C -3.6	A
		T _A =70°C -3.0	
Pulsed Drain Current	I _{DM}	-15	A
Continuous Source Current (Diode Conduction)	I _S	-1.0	A
Power Dissipation	P _D	T _A =25°C 1.20	W
		T _A =70°C 0.8	
Operation Junction Temperature	T _J	150	°C
Storage Temperature Range	T _{STG}	-55/150	°C
Thermal Resistance-Junction to Ambient	R _{θJA}	120	°C/W

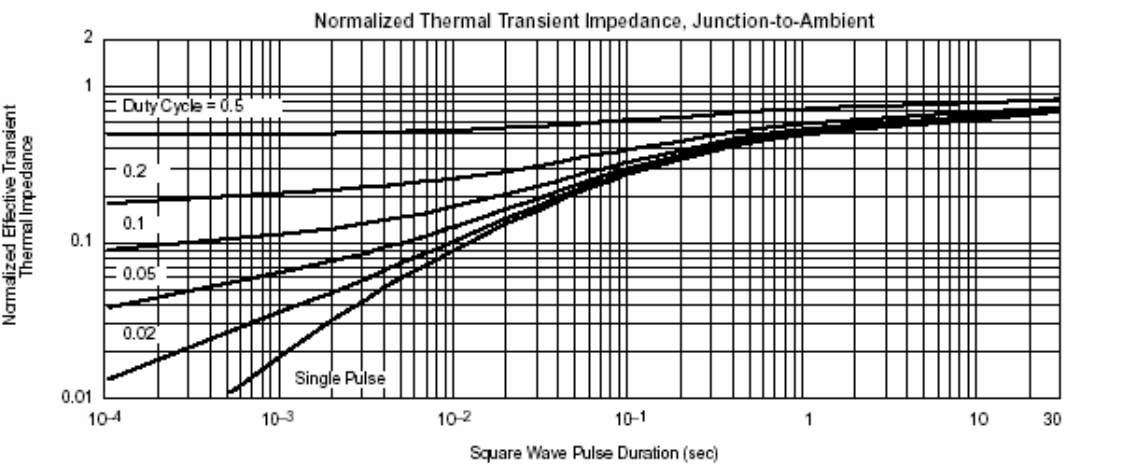
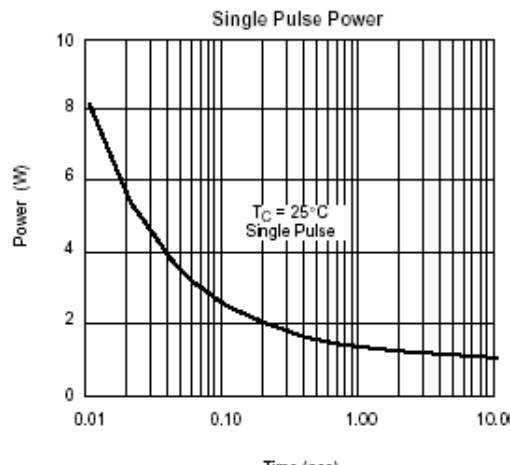
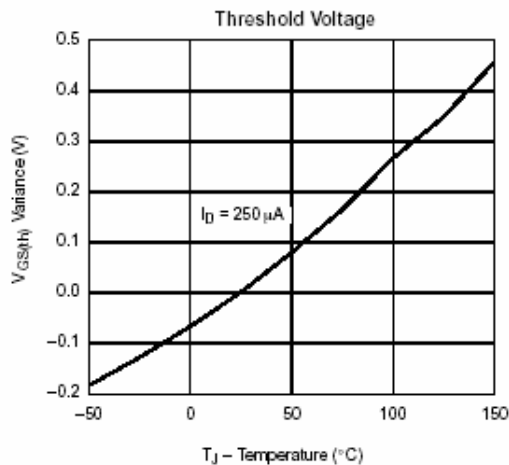
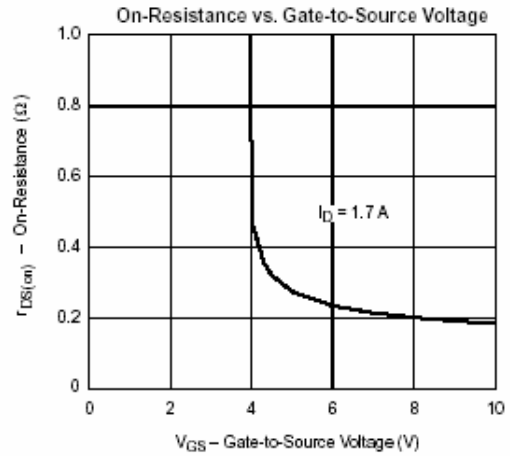
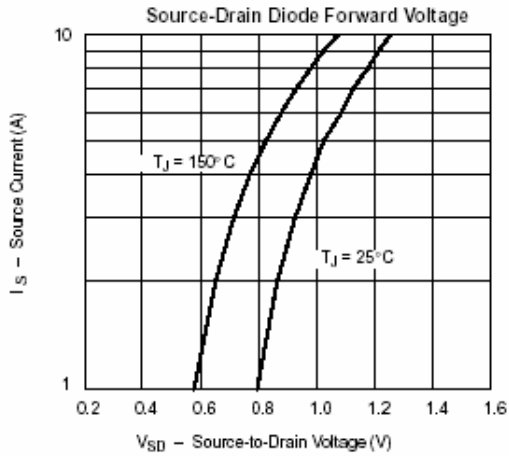
ELECTRICAL CHARACTERISTICS (Ta = 25°C Unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-30			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.0		-3.0	V
Gate Leakage Current	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 20V$			± 100	Na
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-24V, V_{GS}=0V$			-1	UA
		$V_{DS}=-24V, V_{GS}=0V$ $T_J=55^\circ C$			-9.5	
On-State Drain Current	$I_{D(on)}$	$V_{DS}\leq -5V, V_{GS}=-10V$	-10			A
Drain-source On-Resistance	$R_{DS(on)}$	$V_{GS}=-10.0V, I_D=-4.0A$ $V_{GS}=-4.5V, I_D=-3.2A$		55 72	60 80	$m\Omega$
Forward Transconductance	g_{fs}	$V_{DS}=-5.0V, I_D=-4.0A$		10		S
Diode Forward Voltage	V_{SD}	$I_S=-1.0A, V_{GS}=0V$		-0.8	-1.2	V
Dynamic						
Total Gate Charge	Q_g	$V_{DS}=-15V$ $V_{GS}=-10V$ $I_D=-4.0A$		14	21	nC
Gate-Source Charge	Q_{gs}			1.9		
Gate-Drain Charge	Q_{gd}			3.7		
Input Capacitance	C_{iss}	$V_{DS}=-15V$ $V_{GS}=0V$ $F=1MHz$		540		pF
Output Capacitance	C_{oss}			131		
Reverse Transfer Capacitance	C_{rss}			105		
Turn-On Time	$t_{d(on)}$ t_r	$V_{DD}=-15V$ $R_L=15\Omega$ $I_D=-1.0A$ $V_{GEN}=-10V$ $R_G=6\Omega$		10	16	nS
Turn-Off Time	$t_{d(off)}$ t_f			16	25	
				32	50	
				21	32	

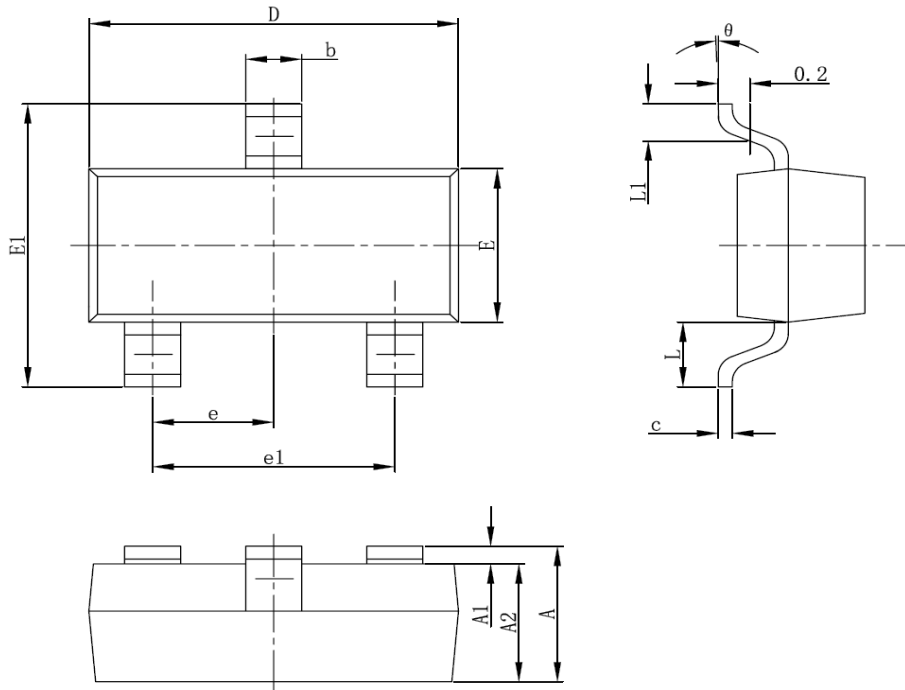
TYPICAL CHARACTERISTICS (25°C unless otherwise noted)



TYPICAL CHARACTERISTICS (25°C unless otherwise noted)



SOT-23 PACKAGE OUTLINE



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950TYP		0.037TYP	
e1	1.800	2.000	0.071	0.079
L	0.550REF		0.022REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°